高登科博会
Golden Tech Expo

2027高登科技产业博览会

Golden Science and Technology Industry Expo 2027

2027.05.27–29

杭州大会展中心–浙江
Hangzhou Grand Convention and Exhibition Center–China

主办及战略单位
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高登会展集团
Golden Conference & Exhibition Group

浙江省人工智能学会
Zhejiang Artificial Intelligence Society

浙江省半导体行业协会
Zhejiang Semiconductor Industry Association

浙江机器人产业发展协会
Zhejiang Robot Industry Association

浙江省计算机信息系统集成行业协会
Zhejiang Computer Information System Integration Industry Association

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AI重塑·智启新程

AI Reshapes the Future, Empowering a New Era

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展会概况
Exhibition Introduction

钱塘潮起，智启新程。新一轮科技革命与产业变革加速演进，人工智能正深度赋能千行百业，新质生产力成为驱动经济高质量发展的核心引擎。人形机器人、集成电路、智能算力、AI智能体等未来产业迎来高速发展窗口期，产业链协同需求持续释放。立足杭州“全国数字经济创新高地”的产业优势，依托长三角强劲创新势能与产业集群势能，由高登会展集团主办的2027高登科技产业博览会（简称“高登科博会”）将于2027年5月27—29日在杭州大会展中心（浙江杭州）举办。展会以“AI重塑·智启新程”为主题，总规划展览面积100,000平方米，致力于搭建前沿科技与未来产业高效对接的高能级平台，助力企业拓展市场、链接资源、塑造品牌。本届科博会设置电子信息制造、半导体与集成电路、电子元器件、智能装备、算力基建、人工智能、机器人与具身智能等展区，并专设未来科创孵化及国际创新合作专区，完整覆盖材料装备、芯片电路、电子组装、光通信算力、感知终端、人形机器人、行业应用、科创生态等产业环节，形成产业闭环。展会围绕展览展示、专业洽谈、供需对接、产业合作、科创孵化与国际合作展开，面向电子信息制造、半导体、电子元器件、智能装备、人工智能、机器人、光通信、新能源配套等领域的专业观众与采购商，促进参展企业与上下游资源、应用场景及国际合作渠道精准对接。届时，展会将汇聚装备制造、汽车、新能源、3C电子、生物医药等领域的企业决策层与技术研发团队，以及系统集成商、科研院所、产业园区、投资机构等高质量专业观众，是展示前沿成果、拓展商业合作、把握未来趋势的重要平台。本届科博会将进一步强化长三角在AI与未来产业领域的引领地位，发挥杭州数字经济的辐射效应，推动区域协同创新与产业联动。

To bring intelligent technologies together in Hangzhou to drive the next stage of industrial development. With the rapid advancement of a new wave of technological revolution and industrial transformation, AI is reshaping industries at an unprecedented pace, while new quality productive forces are becoming a key driver of high-quality economic growth. Humanoid robots, integrated circuits, intelligent computing, AI agents, and other industries of the future are entering a period of rapid growth, and demand for collaboration across their value chains continues to increase. Building on Hangzhou's position as a leading national hub for digital-economy innovation and the Yangtze River Delta's strong innovation capacity and industrial clusters, Golden Conference & Exhibition Group will host the Golden Science and Technology Industry Expo 2027 (Golden Tech Expo) at the Hangzhou Grand Convention and Exhibition Center from May 27 to 29, 2027. Taking "AI Reshapes the Future, Empowering a New Era" as its theme, the expo covers a planned exhibition area of 100,000 square metres, aiming to connect advanced technologies with the industries of the future and help companies expand their markets, connect with resources, and build their brands. It will feature exhibition areas covering electronic information manufacturing, semiconductors and integrated circuits, electronic components, intelligent equipment, computing infrastructure, artificial intelligence, robotics and embodied intelligence. Special zones will focus on innovation incubation and international collaboration, covering materials and equipment, chips and circuits, electronics assembly, optical communications and computing, sensing devices, humanoid robots, industry applications, and innovation ecosystems. Meanwhile, the expo will combine exhibits with professional business meetings, supply-and-demand matchmaking, industry collaboration, innovation incubation, and international cooperation. It will serve professional visitors and buyers in electronic information manufacturing, semiconductors, electronic components, intelligent equipment, AI, robotics, optical communications, and new-energy supply chains, facilitating targeted connections with upstream and downstream partners, application providers, and international business channels. The expo will also bring together executives and R&D teams from equipment manufacturing, automotive, new energy, consumer electronics, and biomedicine, along with systems integrators, research institutes, industrial parks, and investment firms. The show strives to provide a platform to present new technologies, develop business partnerships, and follow emerging industry trends, further strengthening the Yangtze River Delta's role in AI and future industries and extending the influence of Hangzhou's digital economy by promoting regional innovation and industrial collaboration.

展会规模 | Exhibition Area

100,000m²

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关于 HIEM

筑基提质，智创未来。杭州国际电子信息制造业博览会（简称：HIEM）紧扣《电子信息制造业发展“十五五”规划》部署，立足杭州“数字经济第一城”产业优势与长三角电子信息产业集群势能，全面对标“筑基、提质、育新、治理”四大板块、17项重点任务和9个专栏，设置8大核心展区与2个特色专区。展会覆盖集成电路全链条攻关、电子元器件及电子材料高端化、智能传感器创新、电子专用设备及测量仪器自主保障、光子产业突破、先进计算生态、消费电子创新、人工智能硬件底座、能源电子、时空信息、行业电子融合应用等关键环节，打造集展览展示、高端论坛、供需对接、成果转化于一体的专业电子信息产业交流平台。同期举办电子信息制造业高质量发展高峰论坛及十余场专题论坛，汇聚院士专家、产业领袖、行业组织代表及主管部门领导，共议人工智能驱动产业变革、全球产业链重构、关键技术攻关与国产替代、绿色低碳转型等重大议题。

Building a stronger foundation and advancing quality through innovation. The Hangzhou International Electronic Information Manufacturing Industry Expo (HIEM) follows the priorities set out in the 15th Five-Year Plan for the Development of the Electronic Information Manufacturing Industry. Relying on Hangzhou's strengths as a leading digital-economy city and the Yangtze River Delta's electronic information industry cluster, HIEM is aligned with four priority areas, strengthening foundations, improving quality, cultivating new growth, and enhancing governance, as well as 17 key tasks and nine special initiatives. It will feature eight core exhibition areas and two special zones. Furthermore, the exhibits will cover key areas including innovation across the integrated-circuit value chain, the development of high-end electronic components and materials, smart sensor innovation, self-reliance in dedicated electronics equipment and measurement instruments, advances in photonics, the advanced computing ecosystem, consumer electronics innovation, hardware foundations for artificial intelligence, energy electronics, spatiotemporal information, and cross-industry applications of electronics, aiming to establish a national-level platform integrating exhibitions, high-level forums, business matchmaking, and the commercialization of innovations for the electronic information industry. During the exhibition, there are more than ten specialized forums to be held, including the Summit Forum on High-Quality Development of the Electronic Information Manufacturing Industry. Academicians and experts, industry leaders, representatives of industry organizations, and officials from relevant government departments will gather in Hangzhou to discuss major issues related to how AI is driving industrial transformation, the restructuring of global supply chains, breakthroughs in critical technologies and the development of domestic alternatives, and the transition to green, low-carbon development.

亮点 KEY HIGHLIGHT

从一颗芯片到一座智能工厂，从基础材料到行业应用，HIEM Expo 2027以全链视野，助力电子信息制造业高质量发展新征程。

From a single chip to a smart factory, and from basic materials to industry applications, HIEM 2027 takes a full-value-chain perspective to support high-quality development in electronic information manufacturing.

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工业气体被誉为“工业血液”，电子特种气体是半导体制造的“芯片粮食”，约占晶圆制造耗材的14%，直接影响芯片性能与生产良率。展会以“气芯协同·自主创新–构建半导体关键材料安全供应链”为主题，采用“关键材料专项展+半导体全产业链大展”双展联动模式，打通工业气体—电子特气—真空技术—半导体应用完整产业闭环，推动气体企业精准对接半导体终端、半导体企业高效遴选特气供应商，形成双向供需匹配。展会聚焦电子特种气体、高纯制备装备、储运供气系统、半导体材料设备、芯片设计、先进封装测试等核心赛道；真空技术板块覆盖真空获得设备、真空应用设备、真空测量仪器、真空检漏仪器、真空阀门及零部件、真空材料、真空泵油七大板块，集中展示从基础零部件到系统集成设备的全品类产品。依托长三角世界级集成电路产业集群优势，展会贯通“特气原材料、制备装备、检测储运、晶圆制造、封装测试、芯片应用”全产业链条，推动工业气体、电子特气企业与晶圆制造、封测、化合物半导体、光伏显示等终端应用主体深度协作，加速关键材料与装备国产化验证及落地应用，补齐产业链短板，提升供应链安全保障能力。

Industrial gases are often described as the “blood of industry,” while electronic specialty gases are essential process materials for semiconductor manufacturing, accounting for approximately 14% of wafer fabrication consumables, and directly impact on chip performance and manufacturing yield. Taking “Advancing Gas, Semiconductor Collaboration and Independent Innovation to Secure the Supply of Critical Semiconductor Materials” as its theme, the exhibition will unite a specialized exhibition for critical materials with a comprehensive expo spanning the semiconductor value chain. This dual–exhibition model will integrate industrial gases, electronic specialty gases, vacuum technology, and semiconductor applications, while facilitating targeted connections between gas suppliers and semiconductor end users. It will also help semiconductor manufacturers efficiently evaluate and select specialty gas suppliers, improving alignment between supply and demand. The exhibition will focus on key sectors including electronic specialty gases, high–purity gas production equipment, gas storage, distribution and supply systems, semiconductor materials and equipment, chip design, and advanced packaging and testing. The vacuum technology section will cover seven areas, including vacuum generation equipment, vacuum application equipment, vacuum measurement instruments, leak detection instruments, vacuum valves and components, vacuum materials, and vacuum pump oils. Together, they will showcase a comprehensive range of products, from basic components to integrated systems. Building on the Yangtze River Delta’s world–class integrated circuit industry cluster, the exhibition will connect the entire value chain, from specialty gas raw materials and production equipment to testing and storage, wafer fabrication, packaging and testing, and chip applications. It will promote closer collaboration between industrial gas and electronic specialty gas suppliers and end users in wafer fabrication, packaging and testing, compound semiconductors, and photovoltaics and displays. By accelerating the qualification and deployment of domestically developed critical materials and equipment, the exhibition will help address gaps in the industry chain and strengthen supply chain security.

亮点 KEY HIGHLIGHT

气芯协同之势、双展联动之能、真空赋能之效，贯通“工业气体–电子特气–真空技术–半导体应用”全链条，共筑半导体关键材料安全供应链新生态。

Based on gas—semiconductor collaboration, the joint strength of two exhibitions, and the enabling role of vacuum technology, the event will connect industrial gases, electronic specialty gases, vacuum technology, and semiconductor applications, supporting a more secure supply–chain ecosystem for critical semiconductor materials.

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关于 SICE

芯聚钱塘，智联全球。第二届杭州国际半导体与集成电路产业创新展览会（简称“杭州长芯展”）规划30000平方米展览规模，全景呈现从芯片设计到终端应用的全产业链创新解决方案。展会贯通创新链、产业链、资金链、人才链，覆盖EDA工具、芯片设计、晶圆制造、先进封装测试、半导体高端设备、关键电子化学品、第三代半导体、Chiplet、AI算力芯片、存算一体、光子集成、RISC–V生态及全场景终端应用。同期举办全国集成电路人才生态大会、杭州新纪元半导体发展高峰论坛、EDA创新生态论坛、半导体材料装备论坛、光电集成论坛、先进封装技术峰会、智能制造论坛、RISC–V生态共建峰会、产业投资对接会等九大顶级产业峰会，并特别策划浙江省产业链协同对接专场，聚焦人形机器人、新能源汽车、高端医疗电子、工业智能控制等核心应用场景，开展供需发布、精准配对、技术路演等实效活动。展会以“中国集成电路行业年度标杆采购交流盛会、亚洲极具影响力的芯产业创新、投资、贸易平台”为定位，诚邀全球半导体全产业链企业赴钱塘之约，聚芯聚力，共启国产半导体产业高质量发展新征程。

Bringing semiconductor companies together in Qiantang and connecting with the world. The 2nd Hangzhou International Semiconductor and Integrated Circuit Industry Innovation Exhibition (SICE), known as the Hangzhou Semiconductor Innovation Expo, is planned to cover 30,000 square metres and present solutions across the entire value chain from chip design to end applications. It will connect the innovation, industrial, capital, and talent chains, covering EDA tools, chip design, wafer fabrication, advanced packaging and testing, high–end semiconductor equipment, critical electronic chemicals, third–generation semiconductors, Chiplet technologies, AI computing chips, in–memory computing, photonic integration, the RISC–V ecosystem, and applications across end markets. Nine major industry conferences will be held concurrently, including the National Integrated Circuit Talent Ecosystem Conference, Hangzhou New Era Semiconductor Development Summit, EDA Innovation Ecosystem Forum, Semiconductor Materials and Equipment Forum, Photonic Integration Forum, Advanced Packaging Technology Summit, Smart Manufacturing Forum, RISC–V Ecosystem Development Summit, and Industry Investment Matchmaking Conference. A special Zhejiang industry–chain collaboration session will focus on key application areas including humanoid robots, new–energy vehicles, advanced medical electronics, and industrial intelligent control, with supply–and–demand presentations, targeted matchmaking, and technology roadshows. Positioned as an annual benchmark procurement and exchange event for China’s integrated–circuit industry and one of Asia’s influential platforms for semiconductor innovation, investment, and trade, the Expo welcomes semiconductor companies from around the world to meet in Qiantang, build connections, and support the high–quality development of China’s domestic semiconductor industry.

亮点 KEY HIGHLIGHT

链接芯生态，智造新机遇。杭州长芯展，让芯片与场景更近，让创新与交易更实。

Connecting the semiconductor ecosystem to new opportunities. SICE brings chips closer to application scenarios and makes innovation more tangible in the marketplace.

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关于 AICP

智算引领未来，算力赋能百业。杭州国际AI算力产业博览会同期举办杭州国际数据中心液冷技术展览会，以“补链条、建标准、促交易、聚产业、强落地”为宗旨，致力打造国内首个垂直化、全链条、强交易的AI算力专业平台。展会围绕AI算力全产业链与液冷技术全生态，设置AI算力核心硬件、智算中心与基础设施、大模型与算力软件、算力网络与安全、行业算力应用方案、绿色算力与液冷技术、算力生态与服务七大主题展区。从GPU、ASIC、FPGA、NPU、DPU等智算芯片，到高密度AI服务器、液冷服务器、800G/1.6T光模块；从智算中心整体解决方案、模块化智算中心、液冷系统，到通用大模型与行业大模型、算力管理平台、AI开发框架；从算网融合、边缘计算、数据安全与隐私计算，到智能制造、智慧医疗、金融科技、自动驾驶、具身智能等算力解决方案，展会精准聚焦算力产业全链路核心人群，打通算力供需对接壁垒，搭建集技术展示、商务洽谈、项目签约、资源协作为一体的高端产业对接平台。

AI Computing Drives the Future, Powering Industries Across the Economy. The Hangzhou International AI Computing Power Industry Expo will be held concurrently with the Hangzhou International Data Center Liquid Cooling Technology Exhibition. Guided by the goals of strengthening the value chain, developing standards, promoting transactions, bringing the industry together, and accelerating real-world deployment, the events aim to build a specialized, full-value-chain platform for AI computing power with a strong focus on business. The exhibition will cover the entire AI computing value chain and the broader liquid cooling ecosystem, with seven themed zones including AI computing core hardware, intelligent computing centers and infrastructure, foundation models and computing software, AI computing networks and security, industry-specific computing solutions, green computing and liquid cooling technologies, and the computing ecosystem and services. Exhibits will range from GPU, ASIC, FPGA, NPU, and DPU chips to high-density AI servers, liquid-cooled servers, and 800G/1.6T optical modules, from intelligent computing centre solutions, modular centres, and liquid-cooling systems to general-purpose and industry-specific large models, computing management platforms, and AI development frameworks, and from integrated computing networks, edge computing, data security, and privacy computing to solutions for smart manufacturing, smart healthcare, financial technology, autonomous driving, and embodied intelligence. Focusing on key participants across the computing-power industry chain, the event will help remove barriers to matching supply and demand, and provide a high-level platform for technology showcases, business discussions, project signings, and resource collaboration.

亮点 KEY HIGHLIGHT

算力为底座，液冷为支撑，场景为牵引，让智算真正走向千行百业。

Computing power provides the foundation, liquid cooling supports efficient operation, and application scenarios drive adoption, bringing intelligent computing to industries across the economy.

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关于 AI–Token & DSM

融通词元算力，深耕垂类生态。杭州国际AI智能体与词元产业展览会同期举办杭州国际垂类模型及应用大会暨展览会，采用“双展联动、业态互补、资源互通”的一体化办展模式，贯通“词元算力基建—垂类模型研发—AI智能体商用落地”全链条，打造国内垂直化、专业化、落地化的AI全链产业平台。展会设置三大展区：AI词元与算力基建，覆盖算力集群、智算中心、GPU/AI芯片、词元数据集、Token调度系统、数据清洗标注、合规治理、词元流通交易、AI基础工具链；垂类行业模型，覆盖各行业定制化大模型、垂直领域小模型、模型微调、模型蒸馏、MaaS服务、私有化部署、向量数据库、RAG知识库、模型安全审计、评测体系；AI智能体规模化应用，覆盖多Agent智能体、数字员工、行业智能体系统、政企办公智能体、制造智能体、金融智能体、文旅智能体、全场景落地案例与集成解决方案。同期举办杭州词元经济与AI智能体产业大会、杭州垂类模型及应用大会、AI智能体落地与行业标准研讨会、跨境AI创新与数字经济全球化合作论坛等十余场高规格产业活动。

Connecting token computing with industry–specific model ecosystems. The Hangzhou International AI Agent and Token Industry Expo will be held concurrently with the Hangzhou International Domain–Specific Models & Applications Conference and Exhibition. The two events will operate in coordination, complementing each other and sharing resources, to connect the full chain from token–computing infrastructure to industry–specific model development and the commercial deployment of AI agents. Together, they aim to create a specialized, professional, application–oriented platform for the AI industry chain. Three exhibition areas are planned. AI Tokens and Computing Infrastructure will cover computing clusters, intelligent computing centres, GPU and AI chips, token datasets, token scheduling systems, data cleaning and annotation, compliance and governance, token circulation and trading, and AI toolchains. Industry–Specific Models will cover customized large models for different industries, domain–specific small models, model fine–tuning and distillation, Model–as–a–Service (MaaS), private deployment, vector databases, retrieval–augmented generation (RAG) knowledge bases, model security audits, and evaluation systems. Scaled AI–Agent Applications will cover multi–agent systems, digital employees, industry–agent systems, agents for government and enterprise offices, manufacturing, finance, and culture and tourism, as well as application cases and integrated solutions. More than ten high–level industry events will be held concurrently, including the Hangzhou Token Economy and AI Agent Industry Conference, the Hangzhou Industry–Specific Models and Applications Conference, a seminar on AI–agent deployment and industry standards, and a forum on cross–border AI innovation and global digital–economy cooperation.



亮点 KEY HIGHLIGHT

从词元到模型，从模型到智能体，从智能体到真实场景，让AI新质生产力落地有声。

From tokens to models, from models to AI agents, and from AI agents to real–world scenarios, the show will bring the productive potential of AI into practical use.

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核心主题展 Thematic Exhibitions

关于 HMIE

感知驱动未来，光联万物智见。杭州国际精密光学、摄像头技术及应用展览会与杭州国际机器视觉与工业应用展览会形成双展联动、同馆共振。聚焦“光学+AI”融合赛道，打通“精密光学硬件+AI算法应用”全产业链条，构建覆盖技术、产品、应用、生态的全产业闭环；集中呈现从纳米级光学玻璃模压、自由曲面加工设备到亿级像素图像传感器的全链条创新成果；首度实现机器视觉与人形机器人两大前沿领域深度联动，贯通“精准感知—智慧决策—灵巧执行”全技术闭环，构建覆盖核心部件、算法平台、整机系统及多元应用场景的完整产业生态。同期举办国际机器视觉与具身智能大会、杭州精密光学产业大会、智能影像技术论坛、自动驾驶视觉系统峰会、AI与光学深度融合论坛等高规格行业活动。面向汽车工业、新能源、航空航天、医疗器械、精密模具、工业控制、电力电工、轨道交通、通信电子、智能装备、国防军工、智慧物流等行业提供商贸对接、技术交流与资源整合平台。

Perception drives the future and optical technologies connect intelligent systems. The Hangzhou International Precision Optics, Camera Technology and Applications Exhibition and the Hangzhou International Machine Vision and Industrial Applications Exhibition will be held together in the same venue as complementary events. Focused on the convergence of optics and AI, they will connect the full value chain from precision-optics hardware to AI algorithms and applications. The exhibitions will present innovation from nanometre-scale optical glass molding and freeform-surface processing equipment to image sensors with hundreds of millions of pixels. For the first time, machine vision and humanoid robotics will be closely connected, completing the technical loop from precise perception to intelligent decision-making and dexterous execution. The showcase will cover core components, algorithm platforms, complete systems, and diverse application scenarios. Concurrent events will include the International Machine Vision and Embodied Intelligence Conference, Hangzhou Precision Optics Industry Conference, Smart Imaging Technology Forum, Autonomous Driving Vision Systems Summit, and Forum on the Convergence of AI and Optics. The exhibitions will provide business matchmaking, technical exchange, and resource integration for automotive manufacturing, new energy, aerospace, medical devices, precision moulds, industrial control, electrical power, rail transit, communications and electronics, intelligent equipment, defence, and smart logistics.

亮点 KEY HIGHLIGHT

双展同馆之势、全链贯通之能，让机器看得更准，让产业走得更远，共启“光学+AI”新视界。

Two co-located exhibitions connect the value chain and help machines see more accurately, the show will open a new field of possibilities for optics and AI.



高登科博会
Golden Tech Expo

2027. 05.27–29
杭州大会展中心–浙江
Hangzhou Grand Convention and Exhibition Center–China

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关于 SFAE

智造杭州，链动未来。杭州国际智能工厂与工业自动化展览会（简称： SFAE）面向全球工业自动化市场持续高速增长趋势，依托杭州规上工业企业近7500家、28家入围中国制造业500强、正推进“135N”工作体系并培育50家以上“AI工厂”的产业基础，采用“双展协同”“双展同馆、动线咬合”模式，覆盖智能工厂、工业自动化核心部件、工业机器人、人形机器人、电子信息制造全产业链。展会集中展示智能工厂管理系统、工业机器人及智能装备、工业自动化核心部件、工业物联网与数字孪生、智能仓储与物流自动化，以及电子信息制造业全产业链。同期举办杭州国际智能制造高峰论坛，以及AI工厂建设与工业智能体应用、工业自动化与柔性制造、工业互联网与数字孪生、电子信息制造智能化等十余场专题分论坛，组织五场以上精准供需对接会，覆盖汽车零部件、电子信息制造、新能源电池、纺织服装数字化、生物医药等细分行业，定向邀约持有技改预算和批量采购权限的核心买家。展会形成“芯片与元器件–自动化装备与系统–智能工厂应用场景”完整闭环，实现从制造工厂到工厂制造产品的全链条覆盖。

Smart manufacturing in Hangzhou, connecting industries to the future. The Hangzhou International Smart Factory and Industrial Automation Exhibition (SFAE) responds to the continued rapid growth of the global industrial automation market. It draws on Hangzhou's industrial base of nearly 7,500 above-scale industrial enterprises, 28 companies ranked among China's top 500 manufacturers, and the city's ongoing "135N" initiative and efforts to develop more than 50 AI factories. Using a coordinated, co-located exhibition format with integrated visitor routes, SFAE will cover smart factories, core industrial automation components, industrial robots, humanoid robots, and the full electronic information manufacturing value chain. Exhibits will include smart-factory management systems; industrial robots and intelligent equipment; core industrial automation components; the Industrial Internet and digital twins; smart warehousing and logistics automation; and technologies across electronic information manufacturing. The Hangzhou International Smart Manufacturing Summit and more than ten specialist forums will address AI-factory development and industrial-agent applications, industrial automation and flexible manufacturing, the Industrial Internet and digital twins, and intelligent transformation in electronic information manufacturing. More than five targeted supply-and-demand matchmaking sessions will cover automotive components, electronic information manufacturing, new-energy batteries, digital transformation in textiles and apparel, and biomedicine. Core buyers with technology-upgrade budgets and authority to make volume purchases will be invited. The exhibition will connect chips and components, automation equipment and systems, and smart-factory application scenarios—covering the chain from manufacturing plants to the products made in those plants.

亮点 KEY HIGHLIGHT

从单点自动化到整厂智能化，从产线升级到AI工厂，为制造业数智化转型提供全链条选型与采购平台。

From automating individual processes to making entire factories intelligent, and from production-line upgrades to AI factories, SFAE offers manufacturers a full-value-chain platform for selecting and purchasing solutions for digital and intelligent transformation.

高登科博会
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核心主题展 Thematic Exhibitions

关于 HRTE

钱塘潮涌，智启新程。人形机器人正成为全球科技竞争新前沿与产业变革新引擎。第三届杭州国际人形机器人与机器人技术展览会（简称“杭州机器人展”）作为高登科博会旗下核心主题展，以45000平方米超大展区，汇聚1000余家海内外龙头企业与顶尖科研机构，倾力打造人形机器人全产业链高端商贸对接平台。展品全面覆盖整机、仿生灵巧机构、伺服系统、减速器、传感器等核心部件，系统展示工业制造、民生服务、特种作业等全场景智能解决方案，集中呈现人形机器人领域最前沿的技术突破与产业成果。展会深度聚焦前沿技术交流、创新成果转化与产业生态共建，推动国内外技术互通与上下游资源高效协同，为参展企业搭建品牌展示、商贸洽谈、投融资对接、供应链集采一体化合作桥梁。立足钱塘，链接全球，本届展会将助力企业拓展渠道、对接需求、深化合作，激活新质生产力，引领人机共融新赛道。诚邀全球行业同仁齐聚杭州，共襄盛举，携手开创智能产业崭新未来。

Where the qiantang tides rise, the future of intelligent robotics begins. Humanoid robots are rapidly emerging as the new frontier of global technological competition and a powerful engine driving the next wave of industrial transformation. As one of the six themed exhibitions under the Golden Tech Expo, the 3rd Hangzhou International Humanoid Robot & Robot Technology Exhibition will cover a total exhibition area of 45,000 square metres, attracting over 1,000 leading enterprises and top research institutions from around the world. It is dedicated to providing a high-level international business and technology platform for the entire humanoid robotics value chain. The exhibits will comprehensively cover the entire industrial ecosystem, including complete humanoid robot systems, biomimetic dexterous mechanisms, servo systems, precision reducers, and sensors. It will also present intelligent solutions across a wide range of application scenarios, including industrial manufacturing, logistics and warehousing, healthcare, commercial services, household assistance, education, public services, and specialised operations, demonstrating the latest technological breakthroughs and commercial achievements driving the industry's evolution. With a focus on frontier technologies, innovation commercialisation, and ecosystem development, the exhibition strives to promote international technology collaboration and deeper integration across the global humanoid robotics value chain. It is committed to creating an efficient business environment for exhibitors to strengthen market presence, establish strategic partnerships, secure investment opportunities, and connecting with qualified buyers and supply chain partners. Relying on Hangzhou's strengths as a leading innovation hub for the digital economy and intelligent technologies, the exhibition aims to help exhibitors expand global market opportunities, establish high-value partnerships, optimise supply chain collaboration, and accelerate the commercialisation of next-generation humanoid robotics technologies. We cordially invite you to join us in Hangzhou to shape the future of the humanoid robotics industry together.

亮点 KEY HIGHLIGHT

人机共融，万亿赛道，以超大展区、千家全球企业、20万人次专业观众，打造人形机器人全产业链高端商贸对接平台。

Human–Robot Integration and a Trillion-Yuan Market. With a large-scale exhibition area, the event will attract more than 1,000 companies from around the world, and 200,000 professional visitors, aiming to provide a high-level business matchmaking platform covering the entire humanoid robotics value chain.



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主要配套活动
Supporting Activities

- 杭州未来产业大会：汇聚政府主管领导、院士专家、头部企业代表，围绕“AI+机器人+应用”融合创新、物理AI关键技术攻关与商业化落地深度研讨，前瞻研判未来产业新趋势、新赛道、新机遇。
  Hangzhou Future Industries Conference: It will attract government officials, academicians, experts, and representatives of leading companies to explore the convergence of AI, robotics, and real–world applications, advances in key Physical AI technologies, and pathways to commercialization. The conference offers insights into emerging trends, growth sectors, and new opportunities in future industries.

- 杭州人形机器人大会：汇聚国内外顶尖科研专家、行业龙头企业，聚焦技术攻关、产业趋势、商业化落地开展深度研讨，打造人形机器人领域极具影响力的年度会议。
  Hangzhou Humanoid Robot Conference: Leading research experts and companies from China and abroad will discuss hot issues related to technical challenges, industry trends, and commercial deployment, creating an influential annual gathering for the humanoid robotics industry.

- 杭州智能工厂论坛：以“智造升级·产业焕新”为主题，聚焦智能工厂、工业自动化、工业互联网、机器视觉、人形机器人产线融合等方向，邀请制造业龙头、系统集成商、工业软件企业及院士专家，共探智能制造新范式与规模化落地路径。
  Hangzhou Smart Factory Forum: Under the theme of “Smart Manufacturing Upgrade, Industrial Renewal,” the forum will attract leading manufacturers, systems integrators, industrial software companies, and experts to explore smart factories, industrial automation, the Industrial Internet, machine vision, and the integration of humanoid robots into production lines, as well as new models and pathways for large–scale implementation.

- 杭州新纪元半导体发展峰会：围绕第三代半导体、先进封装、Chiplet等前沿方向，研判国内半导体产业突破路径，助力国产替代与产业链自主可控。
  Hangzhou New Era Semiconductor Development Summit: Focusing on third–generation semiconductors, advanced packaging, and Chiplet technologies, it examines pathways to advance China’s semiconductor industry and supports the development of domestic alternatives and a more self–reliant supply chain.

- 杭州电子信息制造业论坛：围绕电子信息制造业创新升级开展交流研讨，聚焦“材料–装备–制造–测试–终端–应用–治理”全链条，推动产业筑基提质、智创未来。
  Hangzhou Electronic Information Manufacturing Forum: It will discuss innovation and upgrading in electronic information manufacturing, focusing on the full chain from materials and equipment through manufacturing, testing, end products, applications, and governance, and promoting stronger foundations, higher quality, and innovation.



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主要配套活动
Supporting Activities

- 杭州AI算力大会：聚焦AI算力基础设施、智算中心建设、数据中心节能改造与低碳运营，分享绿色算力建设实践经验，推动算力产业高效、绿色、可持续发展。
  Hangzhou AI Computing Conference: Focusing on AI computing infrastructure, intelligent computing centre development, energy–efficiency upgrades and low–carbon operations in data centres, it will share practical experience in building green computing capacity and support the efficient, green, and sustainable development of the computing industry.

- 杭州数据中心液冷产业大会：以“智算赋能新基建·绿色低碳双碳行”为主题，搭建技术交流、商贸对接、成果转化的产业交互平台，推动液冷技术规模化商用与行业标准完善。
  Hangzhou Data Center Liquid Cooling Industry Conference: Under the theme of “Intelligent Computing for New Infrastructure, Advancing Green and Low–Carbon Development,” it will provide a platform for technical exchange, business matchmaking, and commercialization, promoting the large–scale adoption of liquid–cooling technology and the development of industry standards.

- 杭州词元经济论坛：围绕词元经济生态、Token创新基地、结算枢纽建设及AI智能体商业化落地开展前沿研讨，探索人工智能商业化新范式与新路径。
  Hangzhou Token Economy Forum: It will discuss the token–economy ecosystem, token innovation bases, settlement hubs, and commercial deployment of AI agents, exploring new models and pathways for commercializing artificial intelligence.

- 杭州垂类模型应用大会：聚焦行业垂类大模型研发，推动大模型技术在制造业等实体经济领域深度落地，加速AI从技术能力走向场景价值。
  Hangzhou Domain–Specific Models and Applications Conference: Focusing on the development of industry–specific large models and application in manufacturing and other parts of the real economy, it aims to help AI move from technical capability to value in real–world scenarios.

- 全产业链精准供需对接会：建立常态化对接机制，促进整机企业、零部件厂商、软件算法企业开展配套合作，促成产业供需匹配，推动创新链、产业链、资金链、人才链深度融合。
  Entire Value Chain Supply–and–Demand Matchmaking: A regular matchmaking mechanism will connect complete–robot manufacturers, component suppliers, and software and algorithm companies, facilitate supplier collaboration and demand matching, and promote deeper integration across innovation, industry, capital, and talent.



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参展费用
Exhibition Area Distribution

★ 标准展位：
A：国内企业：标准展位16800.00/展期（RMB）3m×3m
B：国外企业：标准展位4800.00/展期（USD）3m×3m
展位包括：三面白色壁板、中（英）文楣牌制作、咨询桌一张、折椅二把、地毯满铺、展位 照明、220V/5A电源插座一个、废纸篓一个。）

★ 室内光地：
A：国内企业：1600（RMB）/平方米
B：国外企业：480（USD）/平方米
注：（最少36平方米起租）“光地”只提供参展面积，不包括展架、展具、地毯、电源等。

International Standard Booths:
For overseas enterprises: USD 4800.00/Expo; 3m×3m
Each standard booth consists of 3–sided white wallboards, Chinese& English fascia board, 1 consultation desk, 2 folding chairs, fully–floored carpet, booth lighting system, 1 power socket 220V/5A, and a waste basket.

Indoor Raw Space:
For overseas enterprises: USD 480.00/Sq.m.
Note: The raw space (minimum 36 sq.m.) only supplies a show space excluding stand frames, show equipment, carpet and power supply, etc.



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目标观众
Target Audience

本届高登科博会聚焦AI与未来产业，汇聚全产业链高精度专业观众资源。核心观众涵盖电子信息制造、半导体、电子元器件、智能装备、人工智能、机器人、光通信、新能源配套等领域的专业观众与采购商；装备制造、汽车、新能源、3C电子、生物医药企业的决策层、采购、研发及技术负责人；机器人集成、自动化产线、算力基建、AI落地应用等领域的系统集成商与方案服务商。同时覆盖高校、科研院所、重点实验室及产学研转化团队，各地经信部门、产业园区招商单位，以及专注硬科技、AI、机器人、半导体赛道的投资机构，并吸纳行业代理商、经销商、进出口贸易商、垂直产业媒体与行业协会资源，搭建精准高效的产业对接、技术交流与商贸合作平台。

The expo will focus on AI and future industries, bringing together a highly targeted professional audience across the value chain. It will attract industry professionals and buyers from electronic information manufacturing, semiconductors, electronic components, intelligent equipment, AI, robotics, optical communications, and new energy supply chains. Attendees will also include senior executives, procurement professionals, R&D leaders, and technical decision–makers from equipment manufacturing, automotive, new energy, 3C electronics, and biopharmaceutical companies, as well as system integrators and solution providers working in robotics integration, automated production lines, computing infrastructure, and AI applications. Meanwhile, the event will further welcome representatives from universities, research institutes, key laboratories, and industry–academia–research commercialization teams, local industry and information technology authorities and investment promotion agencies from industrial parks, investors focused on hard technology, AI, robotics, and semiconductors; distributors, dealers, importers and exporters, specialized industry media and trade associations. It aims to provide an effective platform for business matchmaking, technical exchange, and commercial cooperation.



以AI为轴，以全链为脉，以杭州为窗。10万平方米高能级平台，链接未来产业新程，从一颗芯片到一座智能工厂，从词元算力到人形机器人，共赴面向未来的科技盛会。立足杭州“全国数字经济创新高地”，链接长三角创新势能与产业集群，打造覆盖“材料装备–芯片电路–电子组装–光通信算力–感知终端–人形机器人–行业应用–科创生态”的全链条AI与未来产业平台。

With AI at its core, the entire value chain as its backbone, and Hangzhou as its window to the world, the expo will provide a platform for the next generation of industries with an exhibition area of 100,000–square–metre. From a single chip to a smart factory, and from token computing to humanoid robots, it brings together the technologies shaping the future. Rooted in Hangzhou, a leading national hub for digital–economy innovation, and connected to the Yangtze River Delta's innovation strengths and industrial clusters, the exhibits cover the entire industry chain, including materials and equipment, chips and circuits, electronics assembly, optical communications and computing, sensing devices, humanoid robots, industry applications, and innovation ecosystems.

立即报名 | Booth Registration

如欲订“2027高登科技产业博览会”展位，或了解更多信息，请通过以下联络方法：
To book a booth at the “Golden Tech Expo” or for more information, please contact us.

电话：021–64396190　Email: info@goldenexpo.com.cn